

ABSTRACT OF THE DISCLOSURE

A polishing pad for use in chemical mechanical polishing of substrates that being made of fibrous matrix such as cellulose with a binder consisting of thermoset resin material, such as phenolic resin. The polishing surface is ground to form asperities. The polishing pad provides a porous structure by which polishing slurry and polishing debris during chemical mechanical polishing of substrates are stored for subsequent rinsing away, and for enhanced flow-distribution of the polishing slurry. Also disclosed is a method of making the polishing pad.

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